

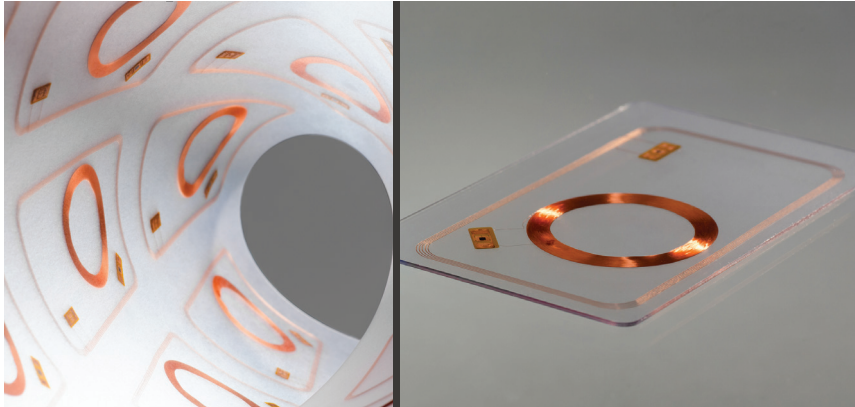


**LINXENS**

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# DUAL FREQUENCY PRELAM®

Higher Efficiency, Diverse Functionality



The LINXENS DUAL FREQUENCY PRELAM® is ideally suited to hybrid applications such as access control, accommodating the growing demand for RFID transponders with various read-range requirements in the standard card format.

Benefits of DUAL FREQUENCY PRELAM:

- Hybrid combination for LF/HF and HF/UHF frequencies available
- Optimized tuning of the antennas
- Highest mechanical durability and longest lifetime

PRELAM stands for “pre-laminated”. This means the fusing together of single layers under pressure and high temperature in a special lamination process to seal the antenna within a homogeneous sheet. The PRELAM structure is ideal for making pre-printed cards with many security features using standard card manufacturing processes.

Available in PVC, PC, PET-G or Teslin® and with a range of chipsets, the LINXENS DUAL FREQUENCY PRELAM complies with all regulatory standards applicable to the respective frequencies.

## Overview

### Operating Frequency

125 kHz  
13.56 MHz  
860-960 MHz

### Operating Temperature

-25°C to +50°C

### Material

PVC, PC, PET-G, Teslin®

## International Standards

- ISO 14443
- ISO 15693
- ISO 18000-6C

## Application Area

- Access Control
- Automated Fare Collection
- Contactless Payment
- Hospitality, Leisure & Entertainment

## Options

- Initialization / customized programming of data



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# DUAL FREQUENCY PRELAM®

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| Operating Frequency                  | Dimensions                         | Thickness*     | Operating Temperature | Available IC  |
|--------------------------------------|------------------------------------|----------------|-----------------------|---|
| <b>125 kHz /<br/>13.56 MHz</b>       | From 3 x 6 up<br>Max. 580 x 705 mm | 400 µm ± 30 µm | -25°C to +50°C        | Atmel<br>EM Marin<br>Infineon<br>Inside<br>LEGIC<br>NXP<br>Samsung<br>Sony<br>STMicroelectronics  |
| <b>13.56 MHz /<br/>860 - 960 MHz</b> | From 3 x 6 up<br>Max. 580 x 705 mm | 400 µm ± 30 µm | -25°C to +50°C        | EM Marin<br>Impinj<br>Infineon<br>Inside<br>LEGIC<br>NXP<br>Samsung<br>Sony<br>STMicroelectronics |

Other thicknesses are available upon request.  
Other chip types are available upon request.